

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 1-3 and add new claims 15-20 as follows:

LISTING OF CLAIMS:

Claims 1-3 (Canceled)

4. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, wherein the heater is adapted to heat the ~~partitioning section~~ member to at least 100°C.

5. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, wherein the heater is adapted to heat the ~~partitioning section~~ member to at least 200°C.

6. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, wherein the heater is adapted to heat the ~~partitioning section~~ member to a temperature at which the adsorption of fluorine onto ~~[[an]]~~ the inner circumferential ~~face~~ faces of the first through-holes and a surface of the ~~partitioning section~~ member is suppressed.

7. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, further comprising a fixing part extending into an interior of the vacuum vessel from a wall thereof and the ~~partitioning section~~ member is attached to the fixing part.

8. (Currently Amended) The apparatus of claim ~~[[3]]~~ 18, further comprising a fixing part extending into an interior of the vacuum vessel from a wall thereof and the ~~partition-section~~ member is attached to the fixing part.

9. (Currently Amended) The apparatus of claim ~~[[1]]~~ 16, wherein the ~~electrically-conductive~~ spiral shield is able to withstand high temperatures of at least about 100° C.

10. (Currently Amended) The apparatus of claim ~~[[3]]~~ 19, wherein the ~~electrically-conductive~~ spiral shield is able to withstand high temperatures of at least about 100° C.

11. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, wherein ~~[[the]]~~ an outer perimeter of the ~~partition-section~~ member is grounded to ~~[[the]]~~ an inner wall of the vacuum vessel.

12. (Currently Amended) The apparatus of claim ~~[[1]]~~ 15, wherein ~~[[the]]~~ an outer perimeter of the ~~partition-section~~ member is mounted to ~~[[the]]~~ an inner wall of the vacuum vessel with an electrically conductive mount.

13. (Currently Amended) The apparatus of claim ~~[[3]]~~ 18, wherein ~~[[the]]~~ an outer perimeter of the ~~partition-section~~ member is grounded to ~~[[the]]~~ an inner wall of the vacuum vessel.

14. (Currently Amended) The apparatus of claim ~~[[3]]~~ 18, wherein ~~[[the]]~~ an outer perimeter of the ~~partition section~~ member is mounted to ~~[[the]]~~ an inner wall of the vacuum vessel with an electrically conductive mount.

15. (New) A substrate treatment apparatus comprising:
a vacuum vessel comprising a first inside-space comprising a first sub-space and a second sub-space;
a member for separating the first sub-space from the second sub-space;
a second inside-space which is formed in the member,
a plurality of first through-holes which communicate between the first sub-space and the second sub-space in a non-contacting manner with the second inside-space;
a second through-hole which communicates between the second inside-space and the second sub-space;
first means for evacuating the first inside-space;
second means in the first sub-space for generating a plasma;
a substrate support mechanism in the second sub-space;
a first gas inlet for introducing a first gas into the second inside-space; and
a second gas inlet for introducing a second gas into the second inside-space;
and
a heater for heating the member so that the adsorption of a cleaning gas onto inner circumferential faces of the first through-holes is suppressed.

16. (New) The substrate treatment apparatus as claimed in claim 15, wherein the substrate apparatus further comprises a spiral shield, and an electrical contact between the member and the vacuum vessel is achieved through the spiral shield.

17. (New) The substrate treatment apparatus as claimed in claim 15, wherein the substrate treatment apparatus is a CVD apparatus.

18. (New) A substrate treatment apparatus comprising:
a vacuum vessel comprising a first inside-space comprising a first sub-space and a second sub-space;
a member made of electrically conductive material for separating the first sub-space from the second sub-space;
a second inside-space which is formed in the member,
a plurality of first through-holes which communicate between the first sub-space and the second sub-space in a non-contacting manner with the second inside-space;
a second through-hole which communicates between the second inside-space and the second sub-space;
first means for evacuating the first inside-space;
second means in the first sub-space for generating a plasma;
a substrate support mechanism in the second sub-space;
a first gas inlet for introducing a first gas into the first sub-space;

a second gas inlet for introducing a second gas into the second inside-space;
and

a heater for heating the member so that the adsorption of a cleaning gas onto inner circumferential faces of the first through-holes is suppressed.

19. (New) The substrate treatment apparatus as claimed in claim 18, wherein the substrate treatment apparatus further comprises a spiral shield, and an electrical contact between the member and the vacuum vessel is achieved through the spiral shield.

20. (New) The substrate treatment apparatus as claimed in claim 18, wherein the substrate treatment apparatus is a CVD apparatus.

21. (New) The apparatus of claim 18, wherein the heater is adapted to heat the member to a temperature at which the adsorption of fluorine onto the inner circumferential faces of the first through-holes and a surface of the member is suppressed.